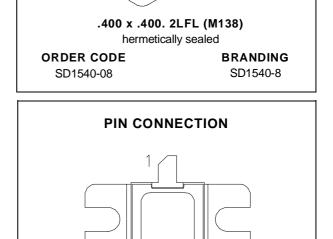


SD1540-08

RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

- DESIGNED FOR HIGH POWER PULSED IFF, DME, TACAN APPLICATIONS
- 350 WATTS (typ.) IFF 1030 1090 MHz
- 300 WATTS (min.) DME 1025 1150 MHz
- 290 WATTS (typ.) TACAN 960 1215 MHz
- 6.3 dB MIN. GAIN
- REFRACTORY GOLD METALLIZATION
- EMITTER BALLASTING AND LOW THERMAL RESISTANCE FOR RELIABILITY AND RUGGEDNESS
- 20:1 LOAD VSWR CAPABILITY AT SPECIFIED OPERATING CONDITIONS
- INPUT/OUTPUT MATCHED, COMMON BASE CONFIGURATION



3. Emitter

4. Base

1. Collector

2. Base

DESCRIPTION

The SD1540-08 is a gold metallized silicon, NPN power transistor designed for applications requiring high peak power and low duty cycles such as IFF, DME and TACAN. The SD1540 is packaged in a metal/ceramic package with internal input/output matching resulting in improved broadband performance and a low thermal resistance.

ABSOLUTE MAXIMUM RATINGS $(T_{case} = 25^{\circ}C)$

Symbol	Parameter	Value	Unit	
V _{CBO}	Collector-Base Voltage	65	V	
V _{CES}	Collector-Emitter Voltage	65	V	
V _{EBO}	Emitter-Base Voltage	3.5	V	
Ic	Device Current	22	А	
Poiss	Power Dissipation	875	W	
TJ	Junction Temperature	+200	°C	
T _{STG}	Storage Temperature	- 65 to +150	°C	

THERMAL DATA

R _{TH(j-c)} Junction-Case Thermal Resistance	0.20	°C/W
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SD1540-08

ELECTRICAL SPECIFICATIONS (T_{case} = 25°C)

STATIC

Symbol	Test Conditions	Value			Unit		
		Min.	Тур.	Max.	Unit		
ВУсво	I _C = 10mA	$I_E = 0mA$		65	_	_	V
BVces	I _C = 25mA	$V_{BE} = 0V$		65	_	_	V
BV _{EBO}	I _E = 5mA	$I_C = OmA$		3.5	_	_	V
ICES	V _{CE} = 50V	$I_E = 0mA$		_	_	25	mA
hFE	V _{CE} = 5V	Ic = 1A		10		_	_

DYNAMIC

Symbol	Test Conditions			Value		
Symbol			Min.	Тур.	Max.	Unit
Pout	f = 1025 — 1150MHz P _{IN} = 70 W	$V_{CE} = 50 V$	300	_	_	W
G _P	f = 1025 — 1150MHz P _{IN} = 70 W	Vce = 50 V	6.3		_	dB
η _C	f = 1025 — 1150MHz P _{IN} = 70 W	V _{CE} = 50 V	35		_	%

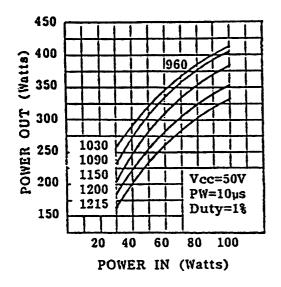
Note: Pulse Width = 10μ Sec, Duty Cycle = 1%

This device is suitable for use under other pulse width/duty cycle conditions.

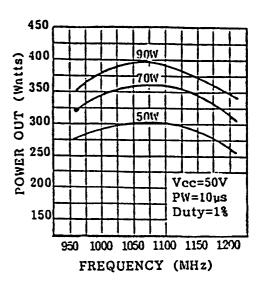
Please contact the factory for specific applications assistance.

TYPICAL PERFORMANCE

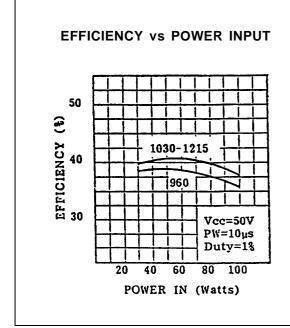
POWER OUTPUT vs POWER INPUT



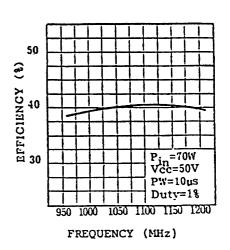
POWER OUTPUT vs FREQUENCY



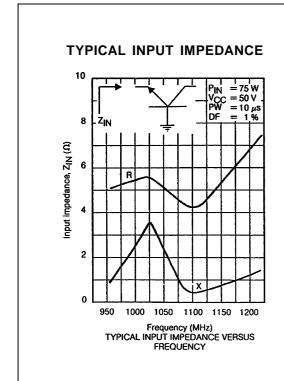
TYPICAL PERFORMANCE (cont'd)



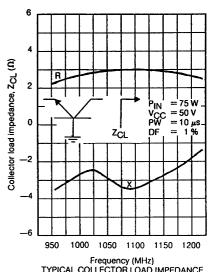
EFFICIENCY vs FREQUENCY



IMPEDANCE DATA

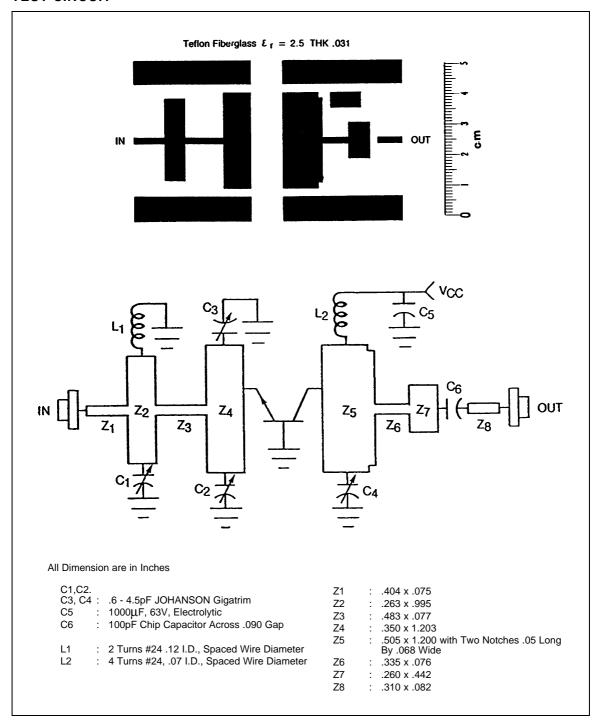


TYPICAL COLLECTOR LOAD **IMPEDANCE**

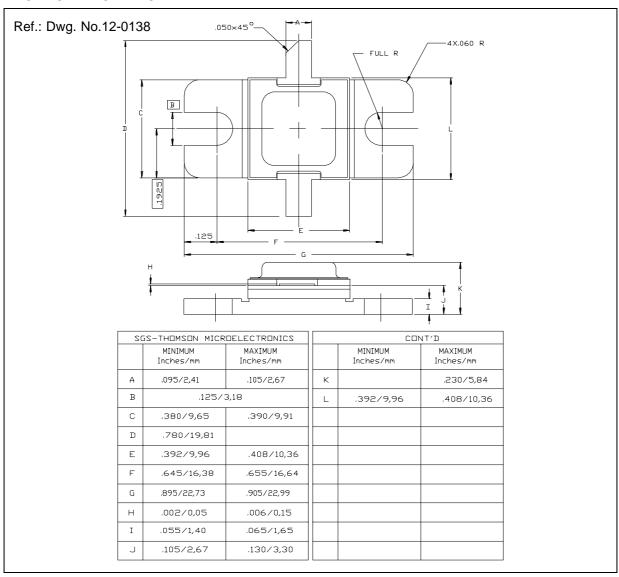


Frequency (MHz)
TYPICAL COLLECTOR LOAD IMPEDANCE
VERSUS FREQUENCY

TEST CIRCUIT



PACKAGE MECHANICAL DATA



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